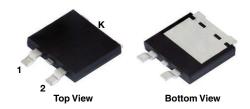


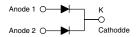
## Vishay General Semiconductor

# Dual High Voltage TMBS® (Trench MOS Barrier Schottky) Rectifier

### eSMP® Series



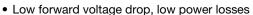
SMPD (TO-263AC)



PRIMARY CHARACTERISTICS			
I <sub>F(AV)</sub>	2 x 5 A		
V <sub>RRM</sub>	170 V		
I <sub>FSM</sub>	100 A		
$V_F$ at $I_F = 5.0$ A ( $T_A = 125$ °C)	0.67 V		
T <sub>J</sub> max.	175 °C		
Package	SMPD (TO-263AC)		
Circuit configurations	Common cathode		

#### **FEATURES**

Very low profile - typical height of 1.7 mm



· High efficiency operation

 Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

AEC-Q101 qualified available



 Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

### TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection.

#### **MECHANICAL DATA**

Case: SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3\_X - halogen-free, RoHS-compliant, and AEC-Q101 qualified

("\_X" denotes revision code e.g. A, B,....)

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

Polarity: As marked

<b>MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER		SYMBOL	V10D170C	UNIT
Device marking code			V10D170C	
Maximum repetitive peak reverse voltage		$V_{RRM}$	170	V
Maximum average forward rectified current (fig. 1)	per device	I <sub>F(AV)</sub>	10	А
	per diode		5	
Peak forward surge current 8.3 ms single half superimposed on rated load	sine-wave	I <sub>FSM</sub>	100	А
Operating junction temperature range		T <sub>J</sub> <sup>(1)</sup>	-40 to +175	°C
Storage temperature range		T <sub>STG</sub>	-55 to +175	°C

#### Note

(1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ 



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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	I <sub>F</sub> = 2.5 A	T 05 °C		0.75	-	
	I <sub>F</sub> = 5 A T <sub>A</sub> = 25 °C	V <sub>E</sub> (1)	0.82	0.9	V	
	I <sub>F</sub> = 2.5 A	T <sub>A</sub> = 125 °C	VF \''	0.6	-	- V
	I <sub>F</sub> = 5 A			0.67	0.74	
Reverse current at rated V <sub>R</sub> per diode	$V_R = 140 \text{ V}$ $T_A = 25 \text{ °C}$ $T_A = 125 \text{ °C}$		0.001	-	mA	
		T <sub>A</sub> = 125 °C	I <sub>R</sub> <sup>(2)</sup>	0.5	-	mA
	V <sub>R</sub> = 170 V	T <sub>A</sub> = 25 °C		-	0.05	mA
	V <sub>R</sub> = 170 V	T <sub>A</sub> = 125 °C		1	3	mA
Typical junction capacitance	4.0 V, 1 MHz		CJ	280	-	pF

#### Notes

 $^{(1)}$  Pulse test: 300  $\mu s$  pulse width, 1 % duty cycle

(2) Pulse test: Pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	V10D170C	UNIT	
Typical thermal resistance per device	R <sub>0</sub> JC (1)	2.5	°C/W	
	R <sub>0</sub> JA (2)(3)	58		

#### **Notes**

- (1) Mounted on infinite heatsink
- (2) The heat generated must be less than the thermal conductivity from junction-to-ambient: dP<sub>D</sub>/dT<sub>J</sub> < 1/R<sub>θJA</sub> junction-to-mount
- (3) Free air, without heatsink

ORDERING INFORMATION (Example)					
PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE	
V10D170C-M3/I	0.55	I	2000/reel	13" diameter plastic tape and reel	
V10D170CHM3_B/I (1)	0.55		2000/reel	13" diameter plastic tape and reel	

#### Note

(1) AEC-Q101 qualified

## **RATINGS AND CHARACTERISTICS CURVES** (T<sub>A</sub> = 25 °C unless otherwise noted)

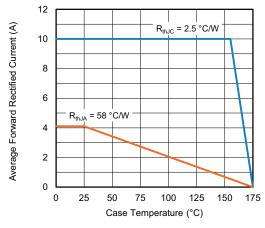


Fig. 1 - Forward Current Derating Curve

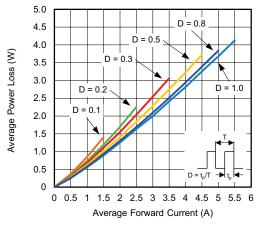


Fig. 2 - Forward Power Loss Characteristics



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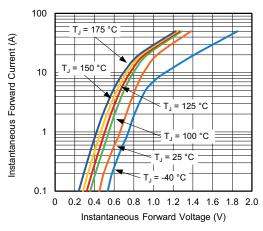


Fig. 3 - Typical Instantaneous Forward Characteristics

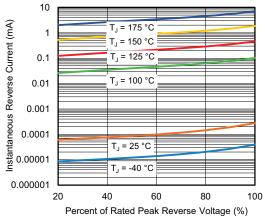


Fig. 4 - Typical Reverse Characteristics

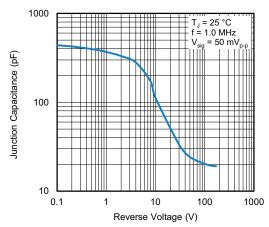


Fig. 5 - Typical Junction Capacitance

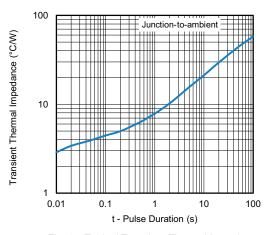


Fig. 6 - Typical Transient Thermal Impedance

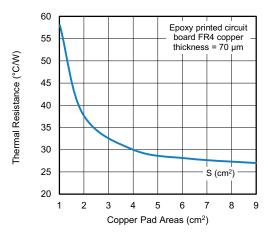
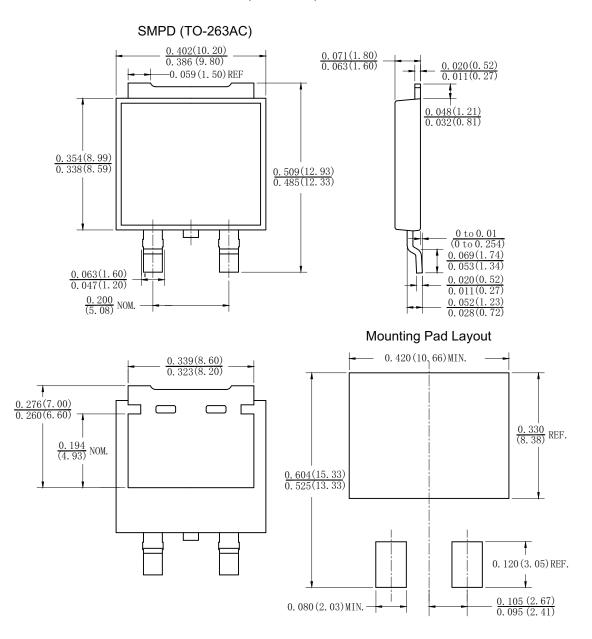


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas



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### PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





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